

LAYER BY LAYER:

Additive Manufacturing Strategies for the FCC-ee Vacuum
System with Focus on the Bake-Out System

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Agenda

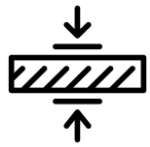
BOS – Bake-Out System

- Key Requirements and Constraints
- Thermal Spraying Technologies
- Materials Selection
- Track Layout Considerations
- Testing of Coatings
- Scale-Up & Manufacturing Integration

SRA – Synchrotron Radiation Absorber

BPM – Beam Positioning Monitor Sockets

BOS – Key Requirements and Constraints



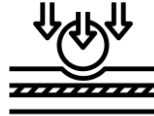
thin



radiation
hardness



non
ferromagnetic



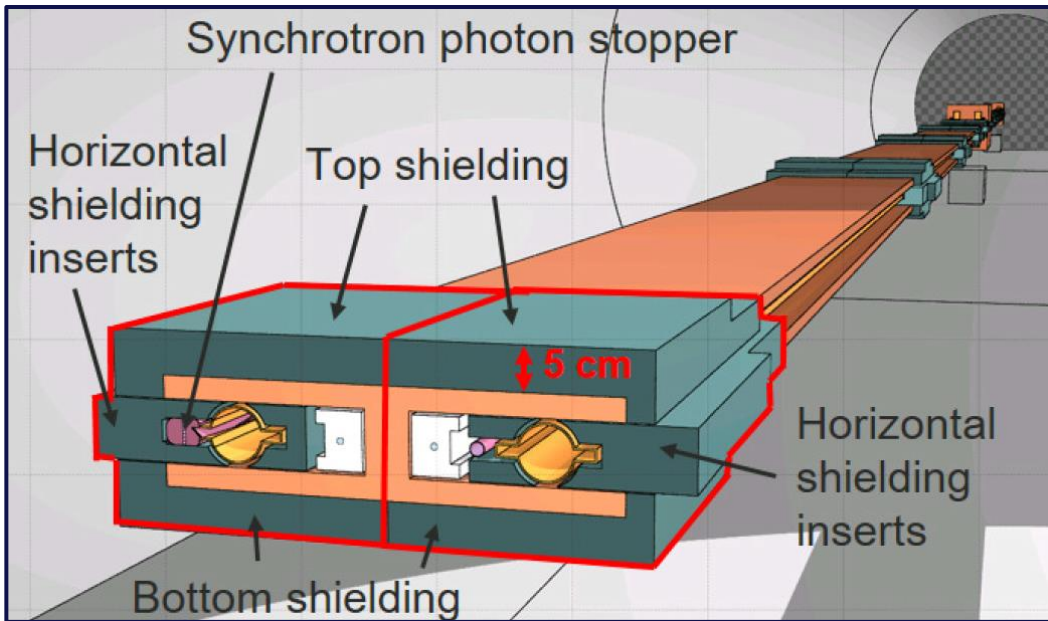
lifetime
durability



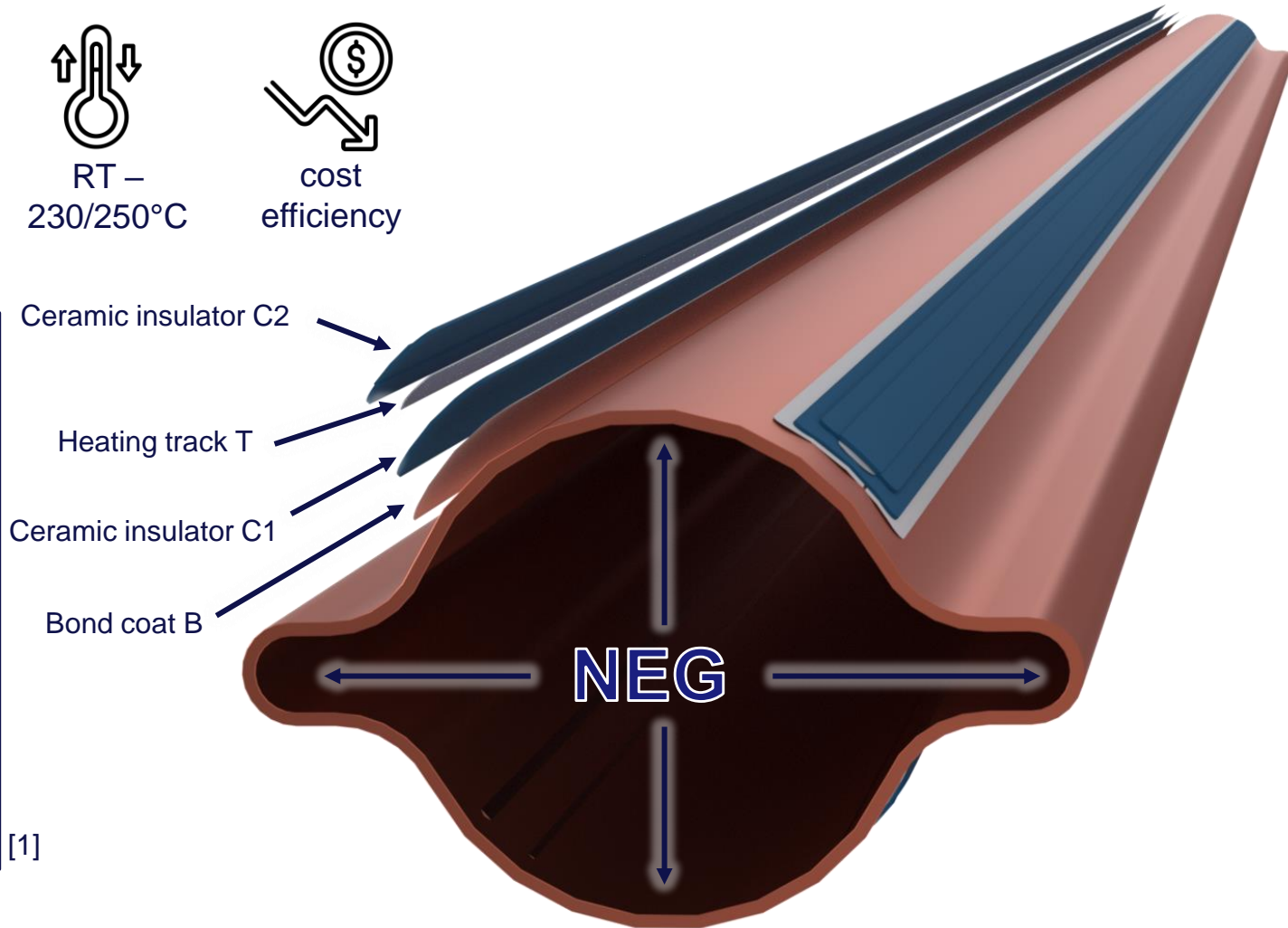
RT –
230/250°C



cost
efficiency



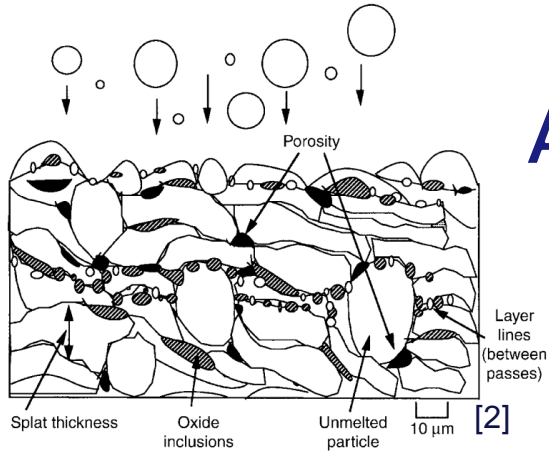
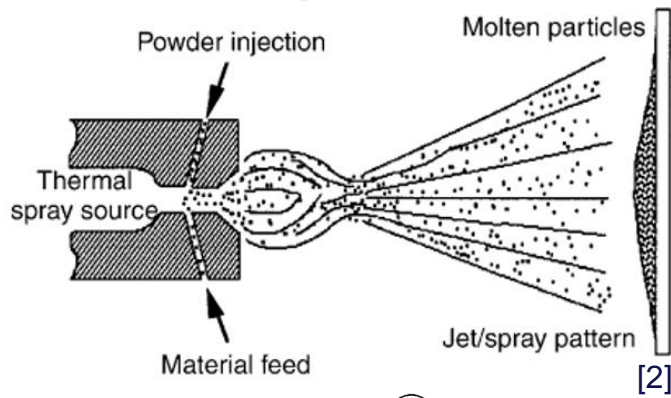
[1]



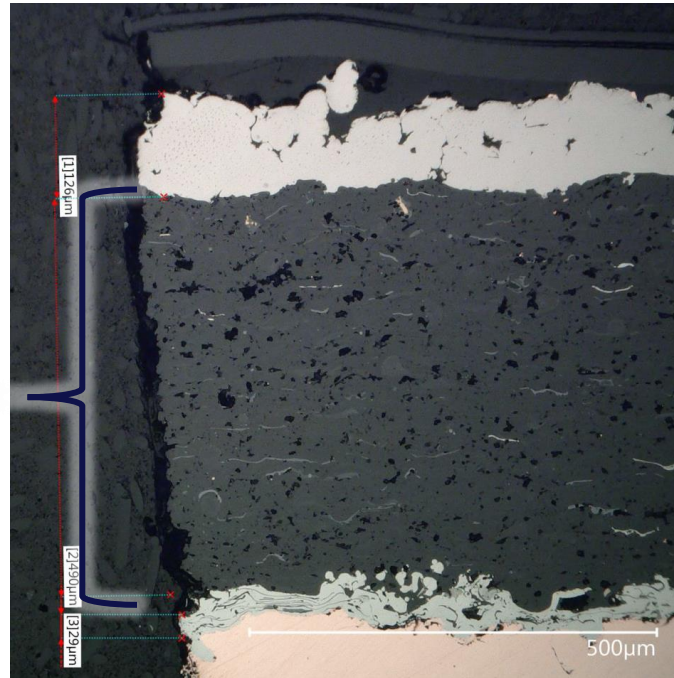
BOS – Thermal Spray Technologies

Atmospheric Plasma Spray (APS):

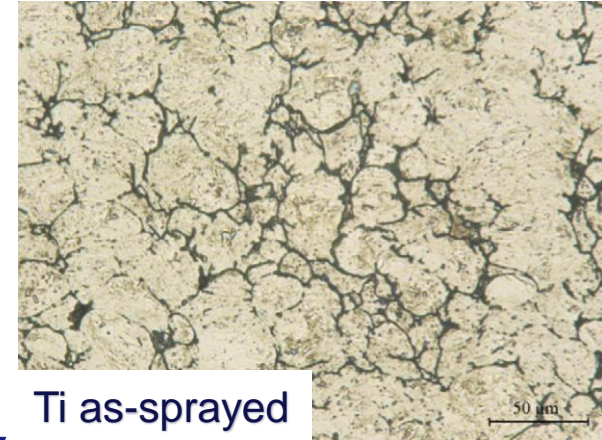
Cold Spray:



APS

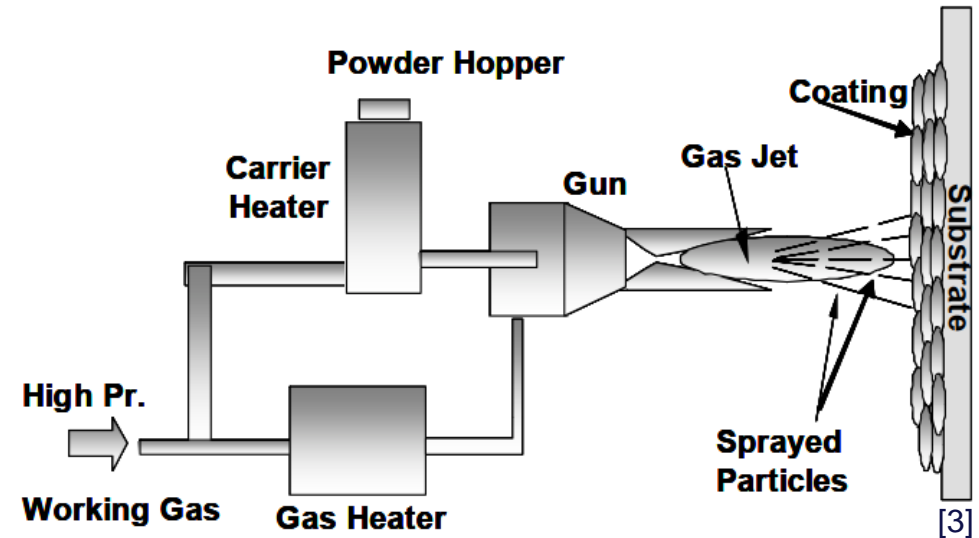


Cold Spray



Ti as-sprayed

[4]



[3]

BOS – Materials Selection – Layer by Layer

Layer	Function	Material		Process
Substrate		Cu-OFS		Extrusion
B	Mediation	NiCr20		APS
C1	Electrical Insulation	Alumina -Titania 87/13	Spinel 72/28	APS
T	Heating	Ti grade 4		Cold Spray
C2	Protection	Alumina -Titania 87/13	Spinel 72/28	APS

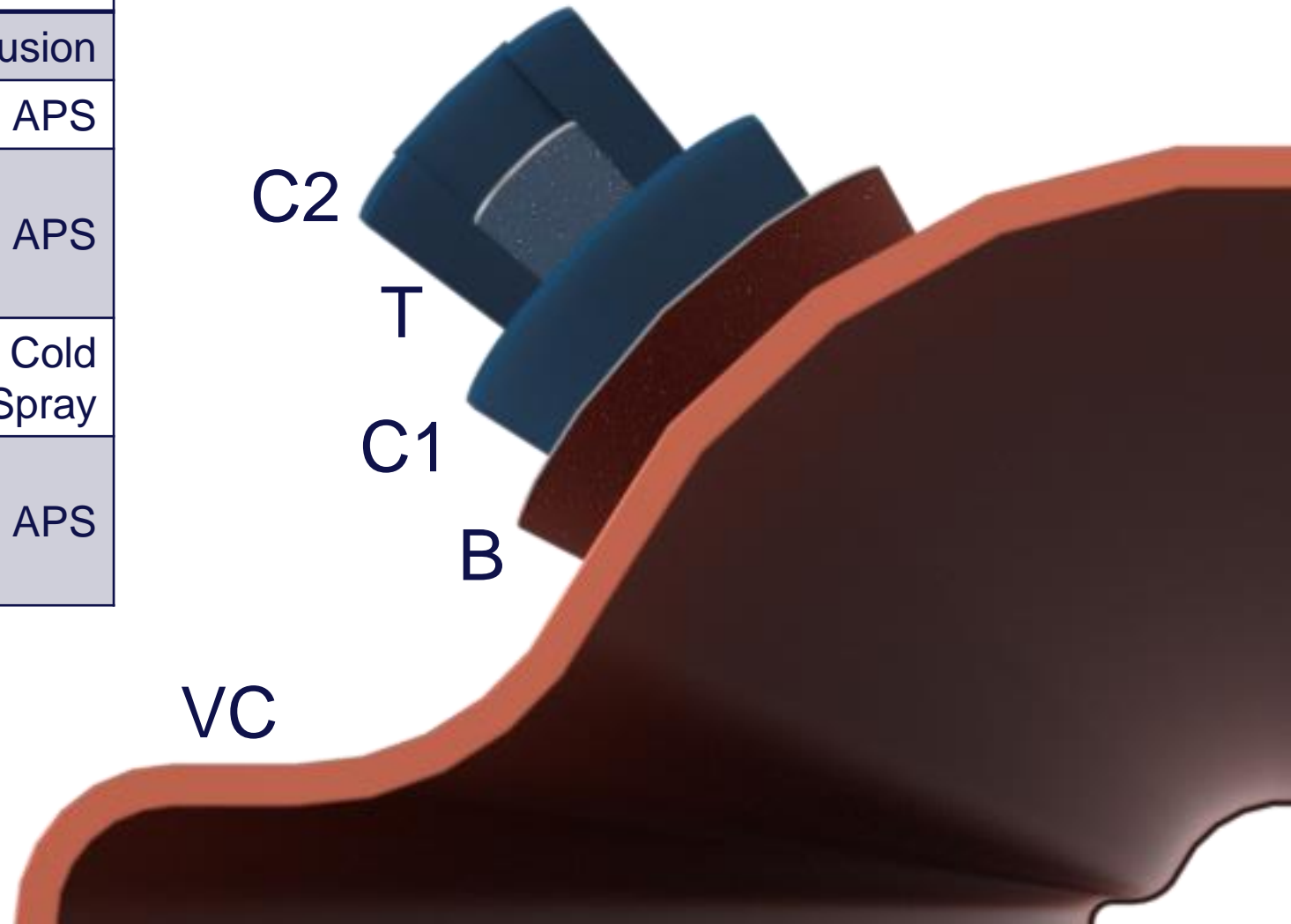
Cu-OFS = Oxygen Free, Silver added Copper (UNS C10700)

Alumina = Al_2O_3

Titania = TiO_2


Magnesia = MgO

Spinel = Alumina-Magnesia

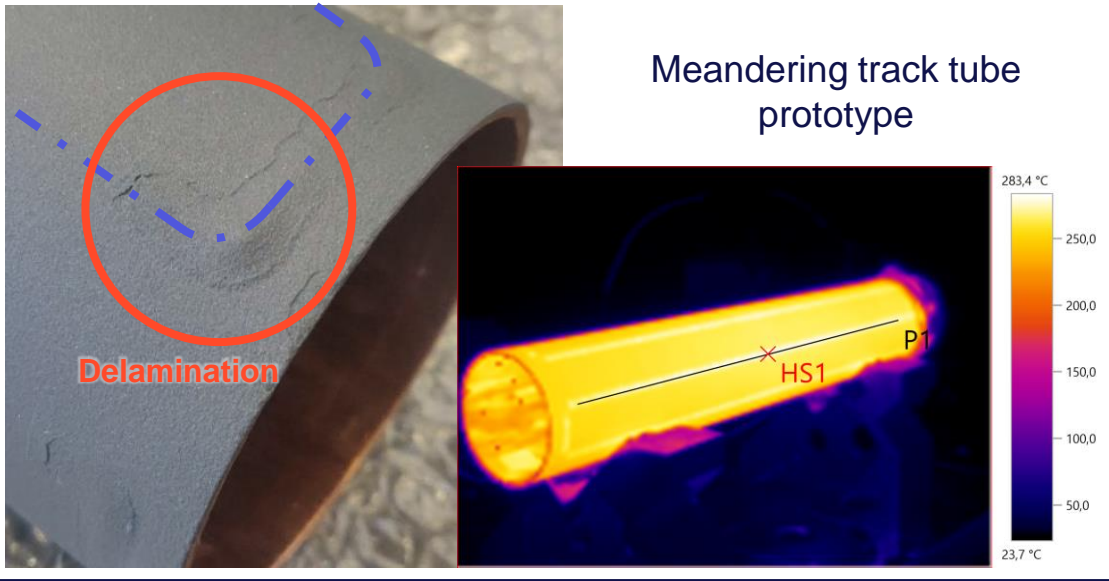


BOS – Meandering vs. Parallel Track Layout

1 continuous track



Meandering track tube prototype



Delamination

HS1

P1

283,4 °C

250,0

200,0

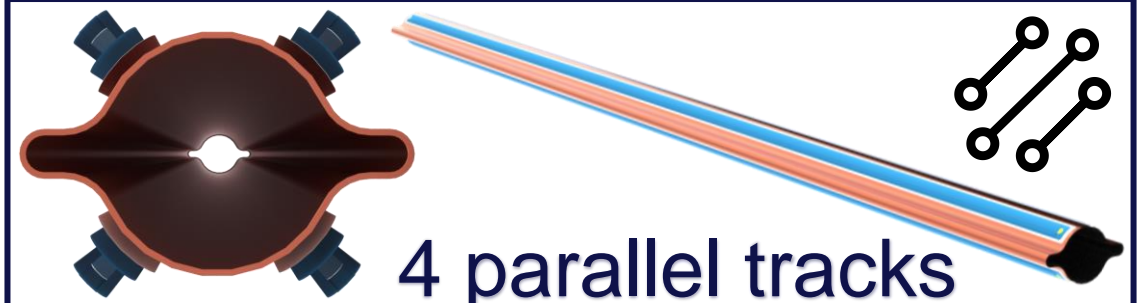
150,0

100,0

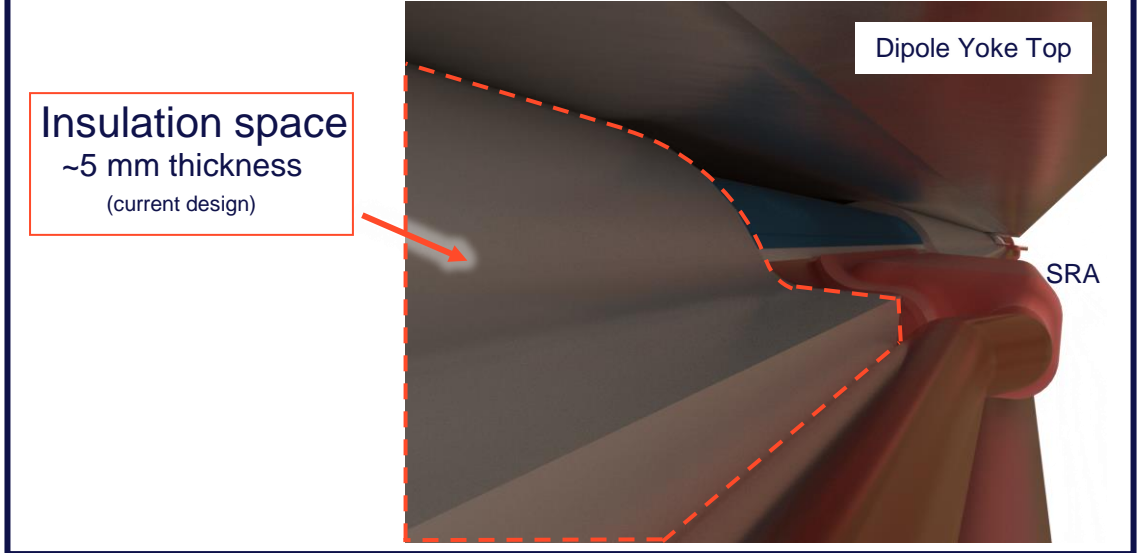
50,0

23,7 °C

4 parallel tracks



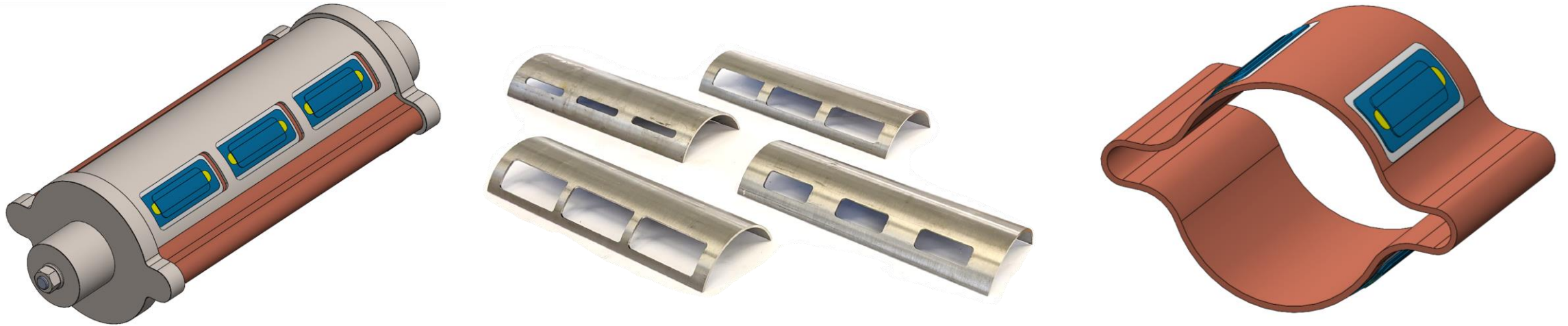
Insulation space
~5 mm thickness
(current design)



Dipole Yoke Top

SRA

BOS – Testing of Coatings



Spraying Setup → Individual mask for each coat → Therm. cycling sample after cutting

Layer	Thickness μm		Material	
B	100		NiCr20	
C1	300	500	Alumina-Titania	Spinel
T	200		Ti grade 4	
C2	500		Alumina-Titania	Spinel

(C2 always same material as C1)

Alumina-Titania 500 μm
Alumina-Titania 300 μm

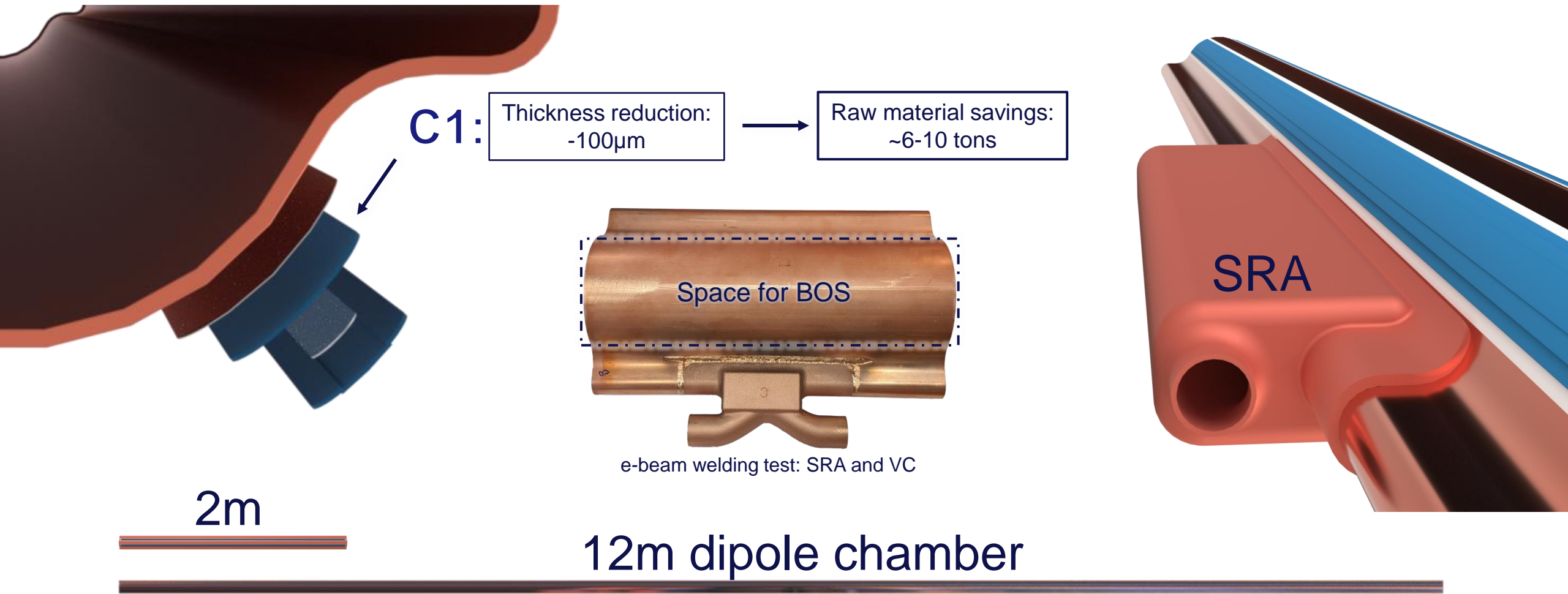
Spinel 500 μm
Spinel 300 μm

4 combinations

Thermal Cycling: 0 – 250°C

- In heat-treatment oven
- Max. 50 cycles
- Parameters tracked every 5 cycles

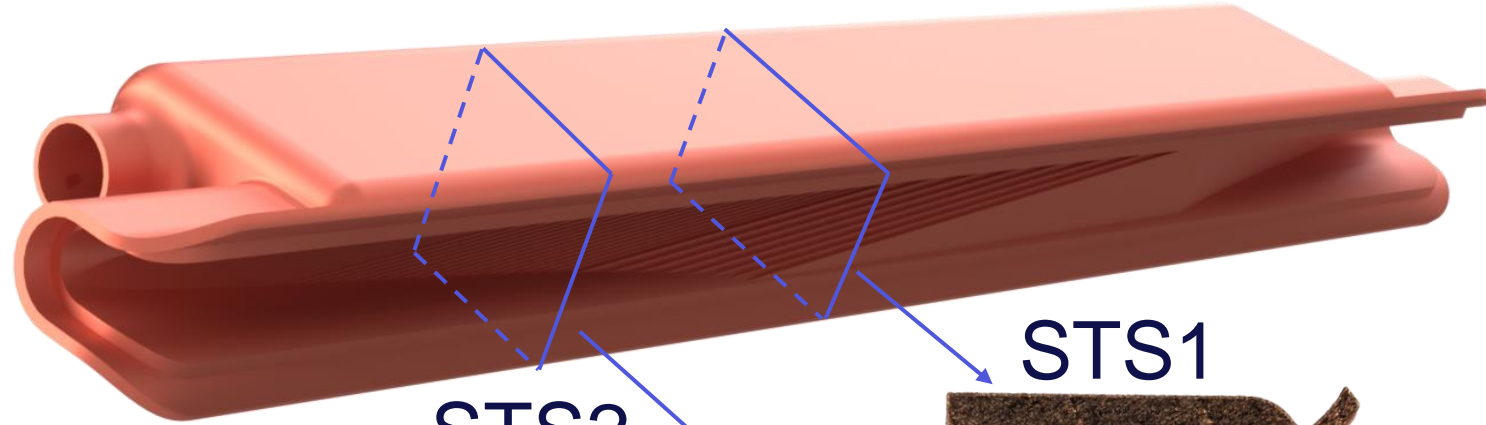
BOS – Scale-Up & Manufacturing Integration





Synchrotron Radiation Absorber & Beam Positioning Monitor Sockets

SRA – Synchrotron Radiation Absorber



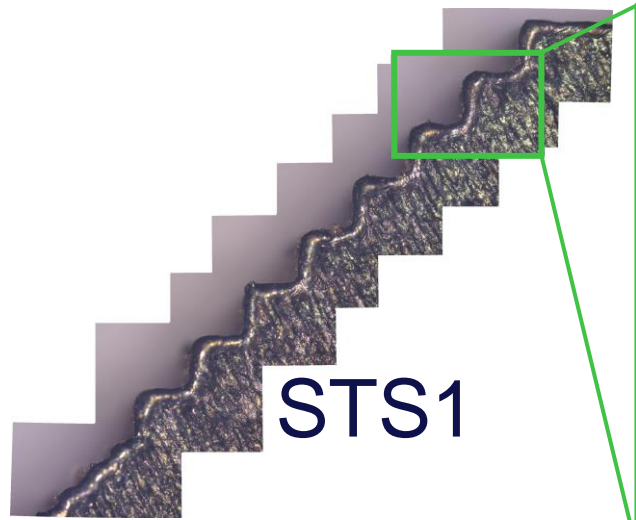
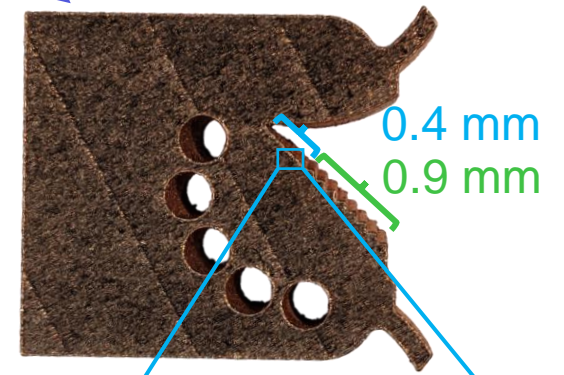
Thermal Characterisation: RT-600°C
 As-printed: CuCP, CuCrZr
 Direct Age Hardened (DAH): CuCrZr

Thermal Expansion
 Specific Heat Capacity
 Thermal Conductivity
 Density (RT only)

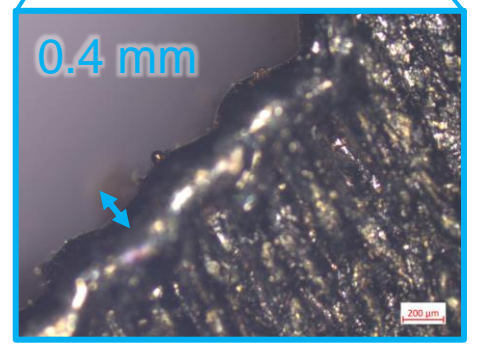
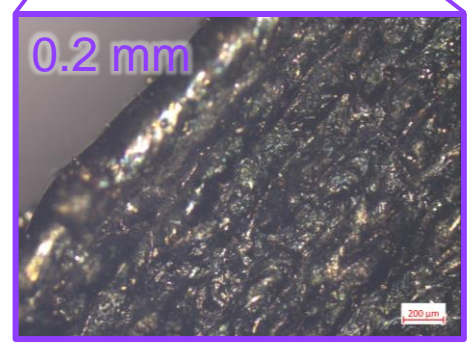
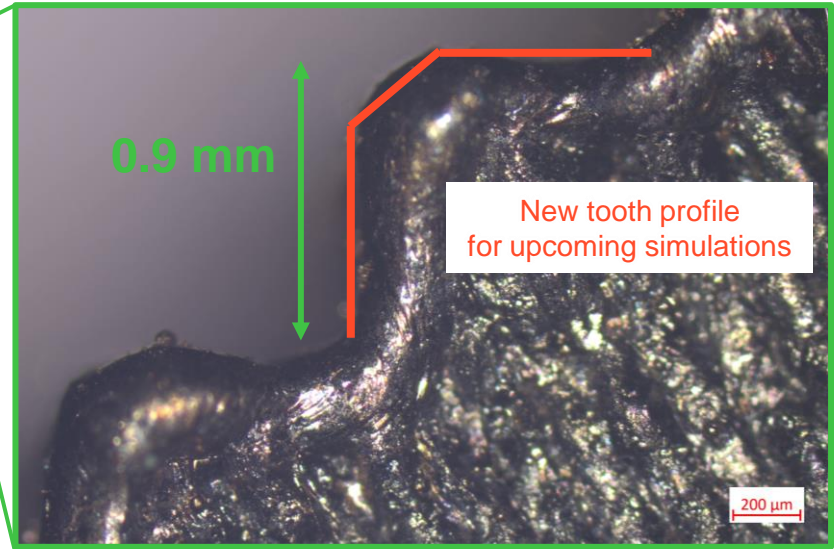
Input for simulations

STS2

STS1



STS1



BPM – Beam Positioning Monitor Sockets



All around



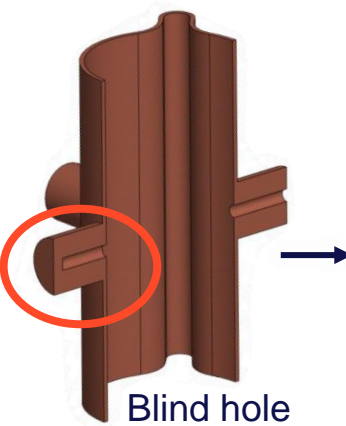
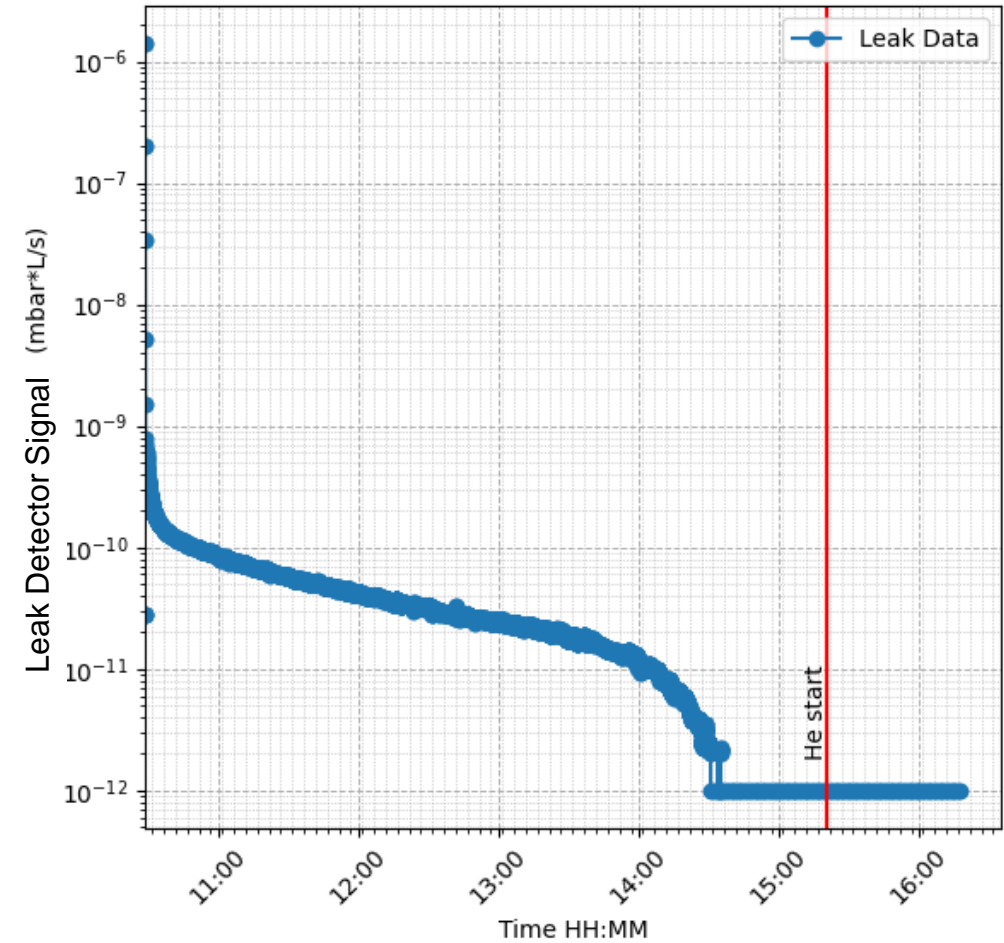
No mask



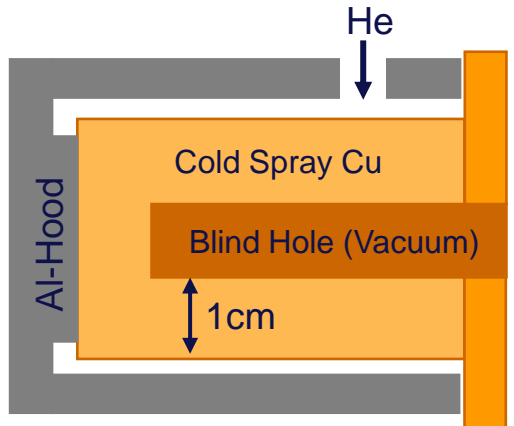
Mask

outer diameter: 26mm

FCC-ee BPM Sockets welded chamber



Blind hole diameter: 6mm



He-injection Setup



Photo of test setup

Thank you for your attention!

BOS-Outlook:

- Production of thermal cycling samples in progress
- Talks with companies for production of big prototypes

SRA-Outlook:

- Heat treatment optimisation study currently under way
- Fatigue and fracture testing campaign with partner institute

BPM Sockets-Outlook:

- Machining of samples for BPM test-fits
- Porosity analysis for spraying strategies
- Mechanical testing campaign including adhesion strength for Cold Spray Additively Manufactured Cu